STFI26NM60N

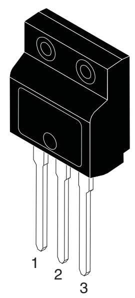
N-channel 600 V, 0.135 Ω, 20 A MDmesh™ II Power MOSFET in I²PAKFP package

Datasheet — production data

Features

Type	V_{DSS}	$R_{DS(on)}$ max	I_D
STFI26NM60N	600 V	< 0.165 Ω	20 A

- Fully insulated and low profile package with increased creepage path from pin to heatsink plate
- 100% avalanche tested
- Low input capacitance and gate charge
- Low gate input resistance



I²PAKFP
(TO-281)

Applications

- Switching applications

Description

This device is an N-channel Power MOSFET developed using the second generation of MDmesh™ technology. This revolutionary Power MOSFET applies a new vertical structure to the company's strip layout to yield a device with one of the world's lowest on-resistance and gate charge, making it suitable for the most demanding high-efficiency converters.

Figure 1. Internal schematic diagram

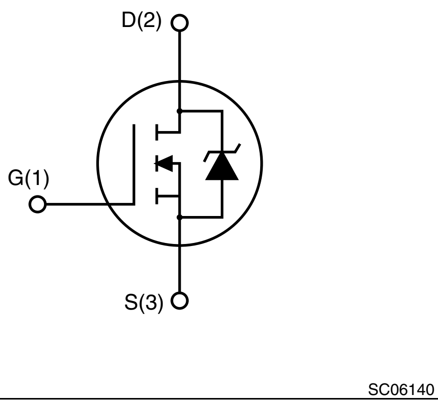


Table 1. Device summary

Order codes	Marking	Package	Packaging
STFI26NM60N	26NM60N	I²PAKFP (TO-281)	Tube

Contents

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	600	V
V_{GS}	Gate-source voltage	± 25	V
I_D	Drain current (continuous) at T_C = 25 °C	20(1)	A
I_D	Drain current (continuous) at T_C = 100 °C	12.6 (1)	A
I_{DM} (2)	Drain current (pulsed)	80(1)	A
P_{TOT}	Total dissipation at T_C = 25 °C	35	W
	Derating factor	0.28	W/°C
dv/dt (3)	Peak diode recovery voltage slope	15	V/ns
V_{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink (t=1 s;T_C=25 °C)	2500	V
T_{stg}	Storage temperature	- 55 to 150	°C
T_j	Max. operating junction temperature	150	°C

1. Limited by maximum junction temperature.
2. Pulse width limited by safe operating area .
3. I_{SD} ≤ 20 A, di/dt ≤ 400 A/µs, V_{DSpeak} ≤ $V_{(BR)DSS}$, V_{DD} = 80% $V_{(BR)DSS}$

Table 3. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case max	3.6	°C/W
$R_{thj-amb}$	Thermal resistance junction-ambient max	62.5	°C/W

Table 4. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AS}	Avalanche current, repetitive or not-repetitive (pulse width limited by Tj max)	6	A
E_{AS}	Single pulse avalanche energy (starting T_J=25 °C, I_D=I_{AS}, V_{DD}=50 V)	610	mJ

2 Electrical characteristics

(T_{CASE} = 25 °C unless otherwise specified)

Table 5. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	I_D = 1 mA, V_{GS} = 0	600			V
I_{DSS}	Zero gate voltage drain current (V_{GS} = 0)	V_{DS} = 600 V V_{DS} = 600 V, T_C= 125 °C			1 100	µA µA
I_{GSS}	Gate-body leakage current (V_{DS} = 0)	V_{GS} = ± 25 V			± 0.1	µA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 250 µA	2	3	4	V
$R_{DS(on)}$	Static drain-source on-resistance	V_{GS} = 10 V, I_D = 10 A		0.135	0.165	Ω

Table 6. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss} C_{oss} C_{rss}	Input capacitance Output capacitance Reverse transfer capacitance	V_{DS} = 50 V, f = 1 MHz, V_{GS} = 0	-	1800 115 1.1	-	pF pF pF
$C_{oss\ eq.}$ (1)	Equivalent output capacitance	V_{GS} = 0, V_{DS} = 0 to 480 V	-	310	-	pF
Q_g Q_{gs} Q_{gd}	Total gate charge Gate-source charge Gate-drain charge	V_{DD} = 480 V, I_D = 20 A, V_{GS} = 10 V, *(see Figure 15)*	-	60 8.5 30	-	nC nC nC
R_g	Gate input resistance	f=1 MHz gate DC Bias=0 test signal level = 20 mV open drain	-	2.8	-	Ω

1. $C_{oss\ eq.}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DS}

Table 7. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r $t_{d(off)}$ t_f	Turn-on delay time Rise time Turn-off delay time Fall time	V_{DD} = 300 V, I_D = 10 A R_G = 4.7 Ω V_{GS} = 10 V *(see Figure 14)*	-	13 25 85 50	-	ns ns ns ns

Table 8. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD} I_{SDM} (1)	Source-drain current Source-drain current (pulsed)		-		20 80	A A
V_{SD} (2)	Forward on voltage	I_{SD} = 20 A, V_{GS} = 0	-		1.5	V
t_{rr} Q_{rr} I_{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I_{SD} = 20 A, di/dt = 100 A/µs V_{DD} = 60 V *(see Figure 16)*	-	370 5.8 31.6		ns µC A
t_{rr} Q_{rr} I_{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I_{SD} = 20 A, di/dt = 100 A/µs V_{DD} = 60 V, T_j = 150 °C *(see Figure 16)*	-	450 7.5 32.5		ns µC A

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration = 300 µs, duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

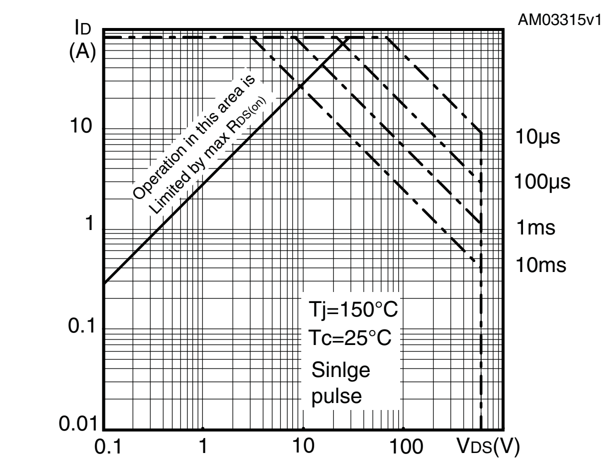


Figure 3. Thermal impedance

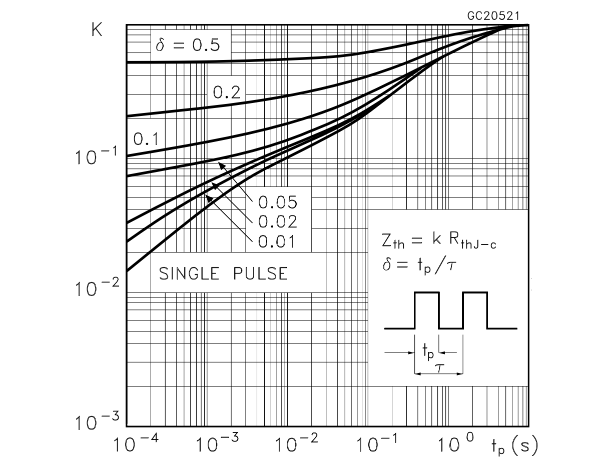


Figure 4. Output characteristics

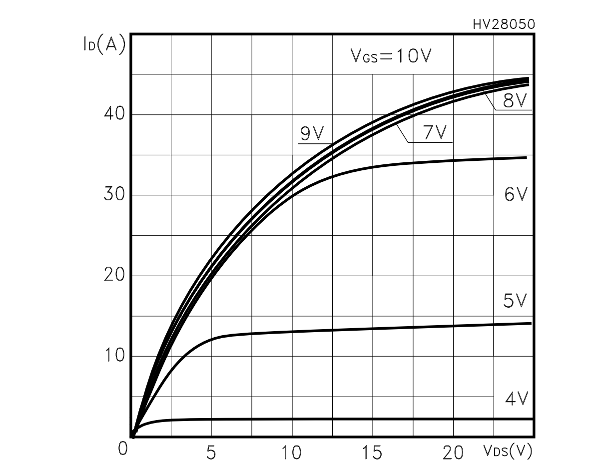


Figure 5. Transfer characteristics

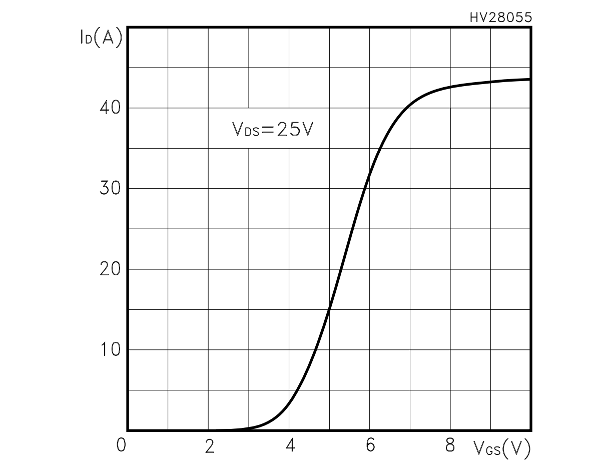


Figure 6. Transconductance

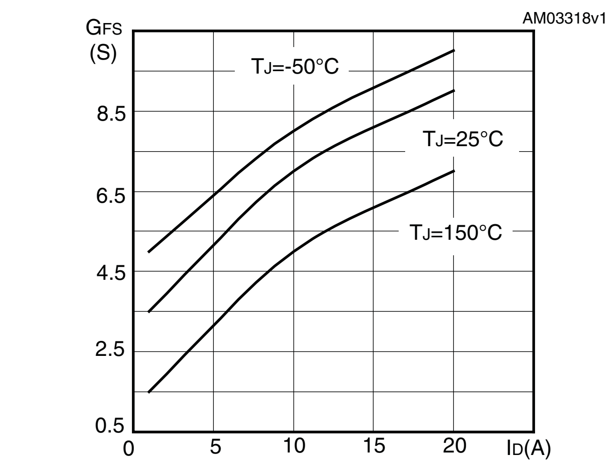


Figure 7. Static drain-source on-resistance

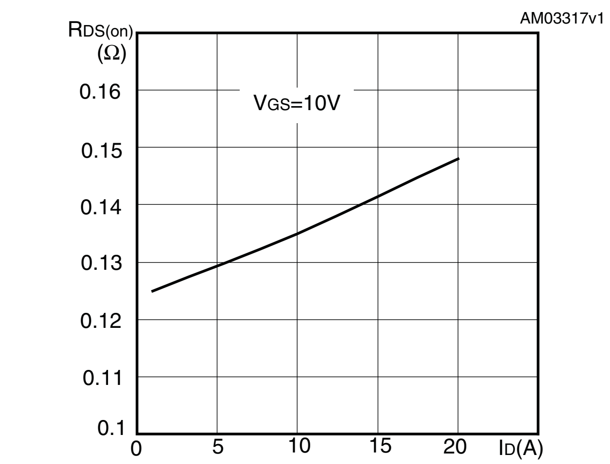


Figure 8. Gate charge vs gate-source voltage

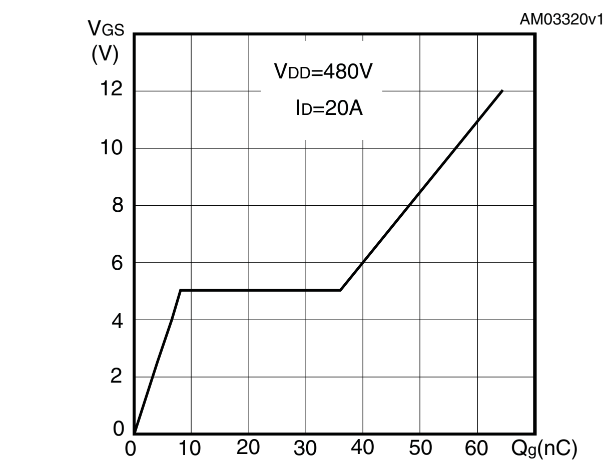


Figure 9. Capacitance variations

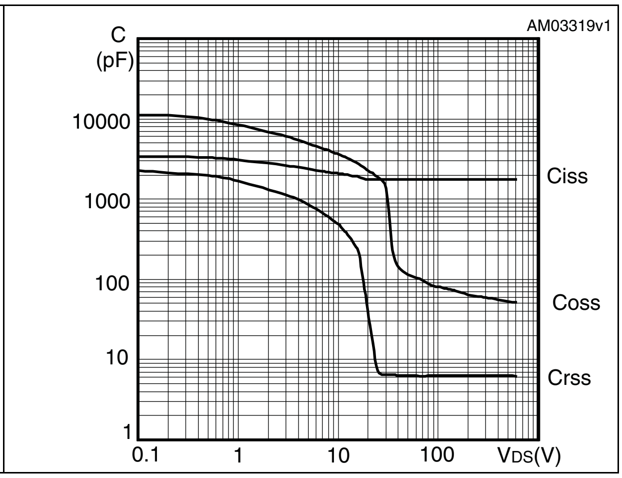


Figure 10. Normalized gate threshold voltage vs temperature

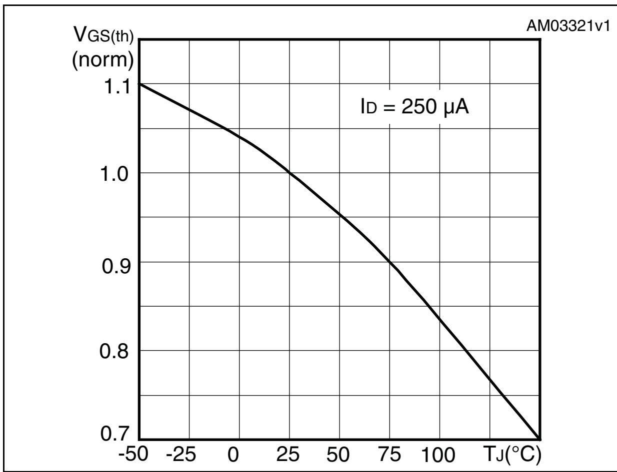


Figure 11. Normalized on resistance vs temperature

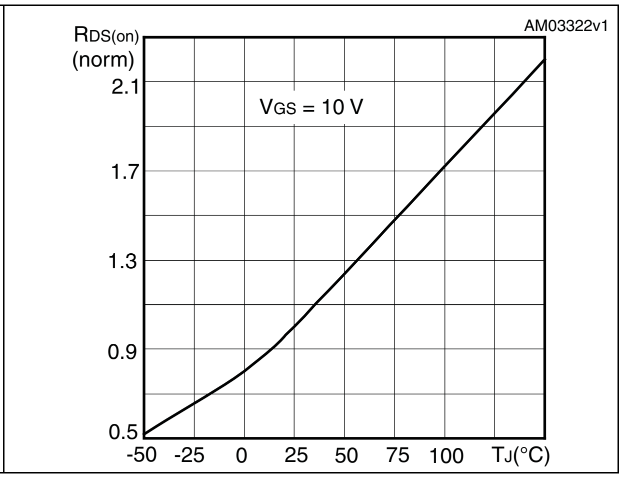


Figure 12. Source-drain diode forward characteristics

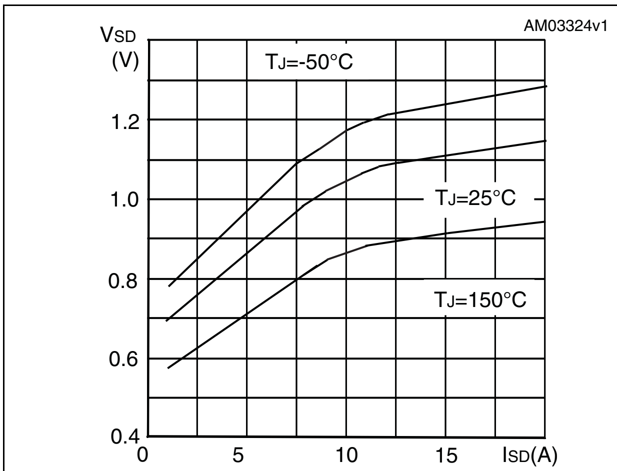
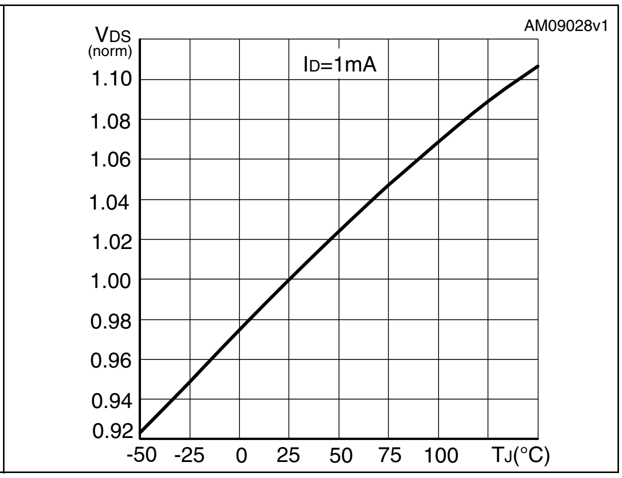


Figure 13. Normalized V_{DS} vs temperature



3 Test circuits

Figure 14. Switching times test circuit for resistive load

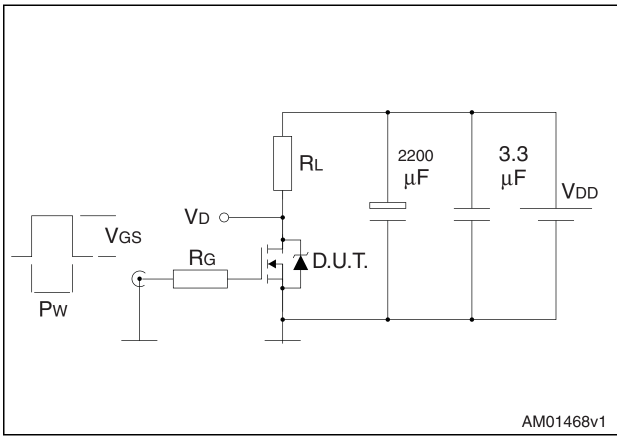


Figure 15. Gate charge test circuit

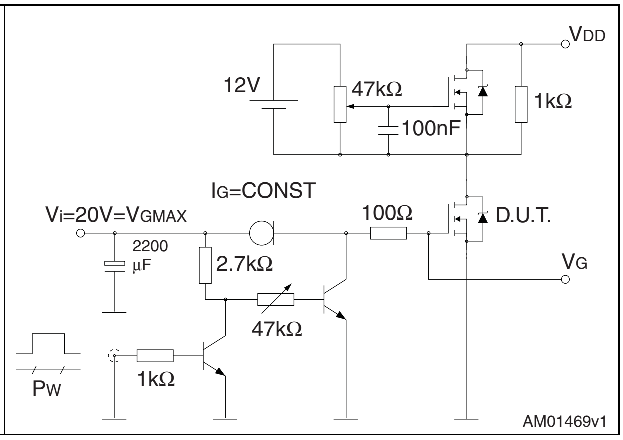


Figure 16. Test circuit for inductive load switching and diode recovery times

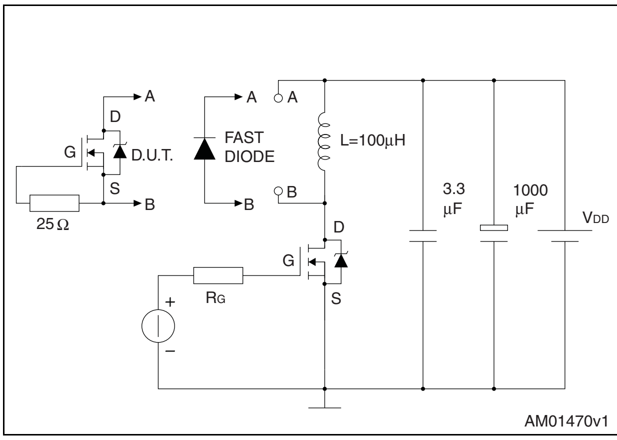


Figure 17. Unclamped inductive load test circuit

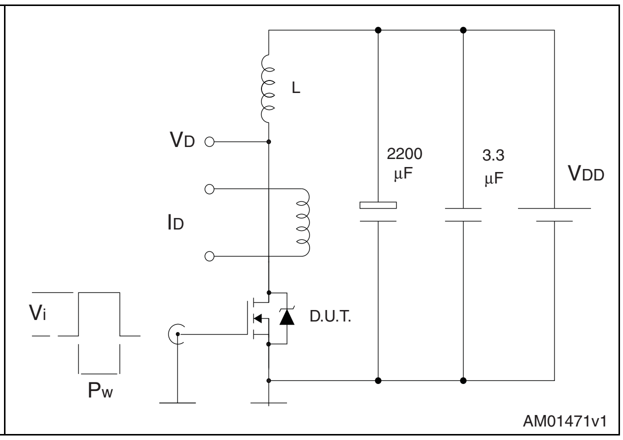


Figure 18. Unclamped inductive waveform

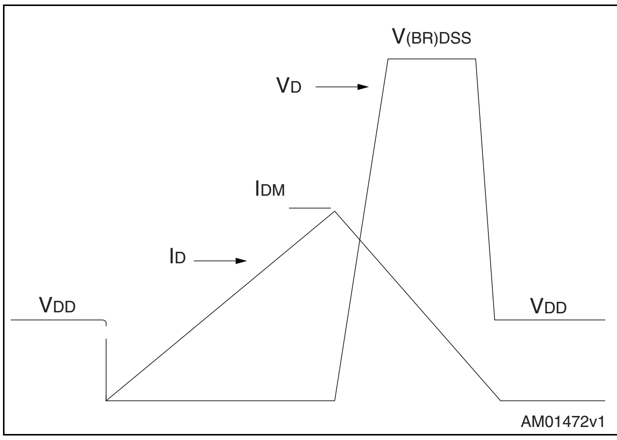
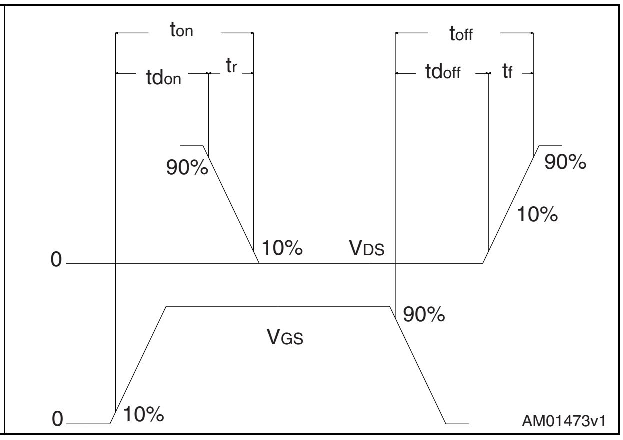


Figure 19. Switching time waveform



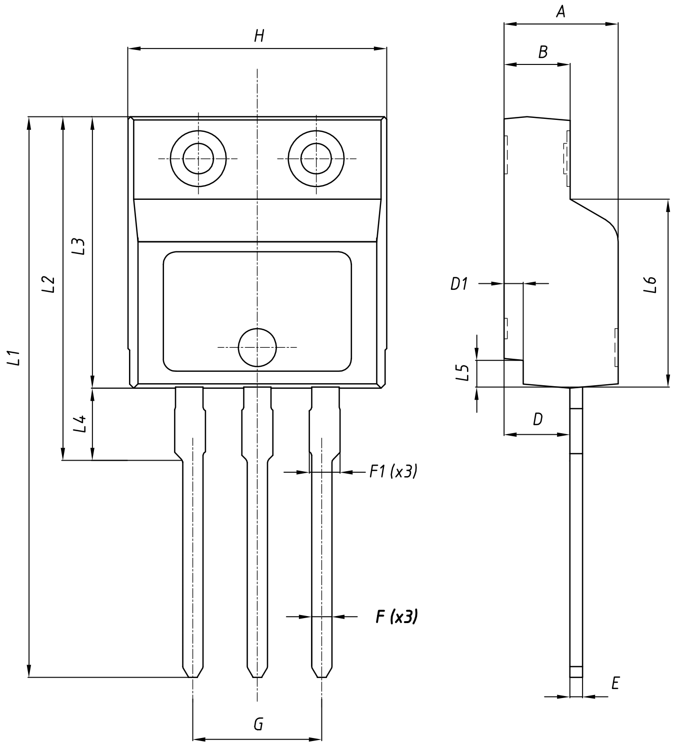
4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

Table 9. I^2PAKFP (TO-281) mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
B	2.50		2.70
D	2.50		2.75
D1	0.65		0.85
E	0.45		0.70
F	0.75		1.00
F1			1.20
G	4.95	-	5.20
H	10.00		10.40
L1	21.00		23.00
L2	13.20		14.10
L3	10.55		10.85
L4	2.70		3.20
L5	0.85		1.25
L6	7.30		7.50

Figure 20. I^2PAKFP (TO-281) drawing



8291506 rev.A

5 Revision history

Table 10. Document revision history

Date	Revision	Changes
15-Nov-2011	1	First release.
04-Jun-2012	2	Document status promoted from preliminary data to production data. Updated P_{TOT} and derating factor values in *Table 2: Absolute maximum ratings*, $R_{th\text{-}case}$ value in *Table 3: Thermal data* Package name has been updated.

Please Read Carefully: